



HSEC8-149-01-L-DV-A



- Board lock option
- Latch option

(0,80 mm) .0315"
HSEC8-DV SERIES

VERTICAL EDGE RATE™ CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material:

- 01=Black Liquid Crystal Polymer
- 03=Natural Liquid Crystal Polymer

Contact:

BeCu

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Current Rating:

3.1A per contact @ 30°C

Temperature Rise

(See website for details)

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3,15 mm) .125" nominal

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (10-60)



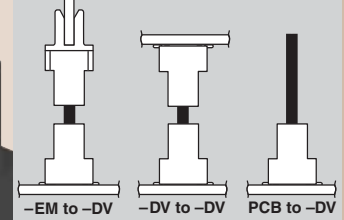
Mates with:
 1,60 mm thick cards,
 ECDP, HSC8, HSF8



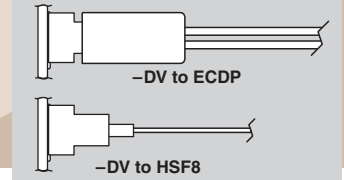
HSEC8 7,98 mm Stack Height	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	8 GHz / 16 Gbps	9 GHz / 18 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps	14 GHz / 28 Gbps

*Performance data includes effects of a non-optimized PCB.
 **Test board losses de-embedded from performance data.
 Complete test data available at www.samtec.com?HSEC8-DV or contact sig@samtec.com

BOARD-TO-BOARD APPLICATIONS

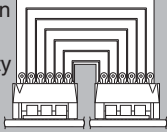


HIGH SPEED CABLE & FLEX APPLICATIONS



STANDARD & CUSTOM CARDS AVAILABLE

- Standard high speed interface cards for 19 mm, 25 mm & 30 mm mated heights, single-ended & differential applications. See HSC8 Series.
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes



APPLICATION SPECIFIC OPTION

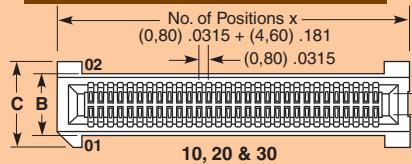
Guide rails and pass-through options. Call Samtec.

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Some lengths, styles and options are non-standard, non-returnable.

HSEC8 - 1 POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - OTHER OPTION

09, 10, 13, 20, 25, 30,
 37, 40, 49, 50, 60



- 01 = (1,60 mm) .062" thick card
- 03 = (2,36 mm) .093" thick card (13, 25, 37, 49 not available)

-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

Note: Other Gold plating options available. Contact Samtec.

-K = (5,50 mm) .217" DIA Polyimide Film Pick & Place Pad

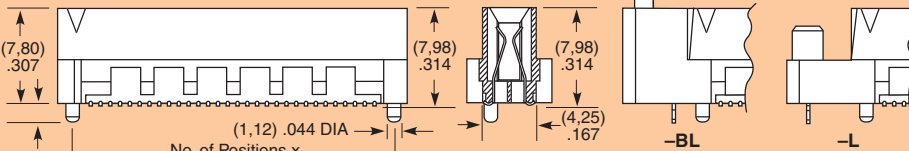
-TR = Tape & Reel Packaging

-L = Latching Option (13, 25, 37, 49 only)

-L2 = ECDP Latching (09, 13, 25, 49 only) (For use with ECDP)

-BL = Board Locks (40, 50, 60 only) (Other sizes available. Contact Samtec.)

-WT = Weld tab



CARD THICKNESS	A	B	C
-01	(1,75) .070	(5,60) .220	(7,00) .276
-03	(2,54) .100	(6,39) .252	(7,79) .307

POSITIONS PER ROW	D	E
09	(4,50) .177	(11,80) .458
13*	(6,10) .240	(15,00) .591
25*	(6,10) .240	(24,60) .969
37	(18,10) .713	(34,20) 1.346
40	(18,90) .744	(36,60) 1.441
49*	(22,90) .902	(43,80) 1.724
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071

Positions where no dimensions are given do not have keying feature.
 *Mates with ECDP Series.

CABLE	CONNECTOR
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2

Due to technical progress, all designs, specifications and components are subject to change without notice.

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